

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

DAE-YOUNG KIM

Application No.:

Filed:

For: **method of manufacturing semiconductor  
device**

Art Group:

Examiner:

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure, enclosed is a copy of Information Disclosure Statement by Applicant (form PTO/SB/08), which is being submitted concurrently with the Utility Application. It is respectfully requested that the cited references be considered and that the enclosed copy of PTO/SB/08 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s). Copies of the references cited on PTO/SB/08 are enclosed herewith.

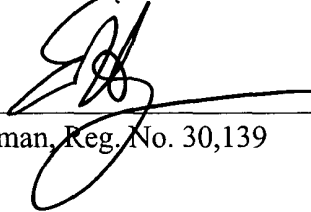
The submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made in the subject application and is not to be construed as an admission that the information cited in this statement is material to patentability.

Please charge any fees due to Deposit Account 02-2666. A duplicate copy of the Fee Transmittal (PTO/SB/17) is enclosed for this purpose.

Date: 8/14/03

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

  
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Substitute for form 1449A/PTO <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> <i>(use as many sheets as necessary)</i>				<b>Complete if Known</b>		
Sheet		1	of	2	Application Number Filing Date First Named Inventor: Dae-Young Kim Art Unit Examiner Name Attorney Docket Number: 51876P356	

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number Number - Kind Code <sup>2</sup> (if known)	Publication Date or Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		US-6525965	02-25-2003	Ghodsi	
		US-6466489	10-15-2002	Ieong et al.	
		US-6355954	03-12-2002	Gall et al.	
		US-6238967	05-29-2001	Shiho et al.	
		US-6211011	04-03-2001	Chen	
		US-6030871	02-29-2000	Eitan	
		US-6025224	02-15-2000	Gall et al.	
		US-5216265	06-01-1993	Anderson et al.	
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> - Number <sup>4</sup> - Kind Code <sup>5</sup> (if known)				
		10-303140	11-13-1998	St. Microelectron SRL		
		09-97898	04-08-1997	Sanyo Electric Co Ltd		

Examiner Signature	Date Considered
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08A (05-03) as modified by Blakely, Solokoff, Taylor & Zafman (wlr) 05/02/2003.



# **Information Disclosure Statement**

New U.S. Patent Application for  
**METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE**  
Our Ref. No.: P03H1054/US/yh

## **Reference No.:**

- (1) US Patent No. 6,525,965
- (2) US Patent No. 6,466,489
- (3) US Patent No. 6,355,954
- (4) US Patent No. 6,238,967
- (5) US Patent No. 6,211,011
- (6) US Patent No. 6,030,871
- (7) US Patent No. 6,025,224
- (8) US Patent No. 5,216,265
- (9) JP Laid-Open No. 10-303140
- (10) JP Laid-Open No. 09-97898